

Surface Mount Yellow Green Chip LED - 0603

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**RoHS
Compliant**

Features

- 1.6mm × 0.8mm SMT LED, 0.7mm Thickness.
- Wide viewing angle.
- Ideal for Backlight and Indicator.
- Various Colours and Lens types available.
- MSL 3.

Applications

- Automotive: Backlighting in dashboard and switch.
- Telecommunication: Indicator and Backlighting in telephone and fax.
- Flat Backlight for LCD switch and symbol.



Device Selection Guide

Part No.	Chip		Lens Colour
MP005928	Material	Emitted Colour	Water clear
	(InGaN)	Green	

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	62	mW
Forward Current	I _F	25	mA
Peak Forward Current*1	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-40°C To +85°C	
Storage Temperature	T _{stg}	-40°C To +85°C	

Notes:

*1: Pulse width≤0.1ms, Duty cycle≤1/10

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Typ.	Max	Unit	Test Conditions
Forward Voltage	V _F	1.8	—	2.6	V	I _F =20mA
Reverse Current	I _R	—	—	10	μA	V _R =5V
Dominate Wavelength	λ _D	566	—	576	nm	I _F =20mA
Luminous Intensity	I _V	48	—	100	mcd	I _F =20mA
Viewing Angle	2θ1/2	—	120	—	Deg.	I _F =20mA

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:

1. wavelength: ±1nm
2. Luminous Intensity: ±15%
3. Forward Voltage: ±0.1V

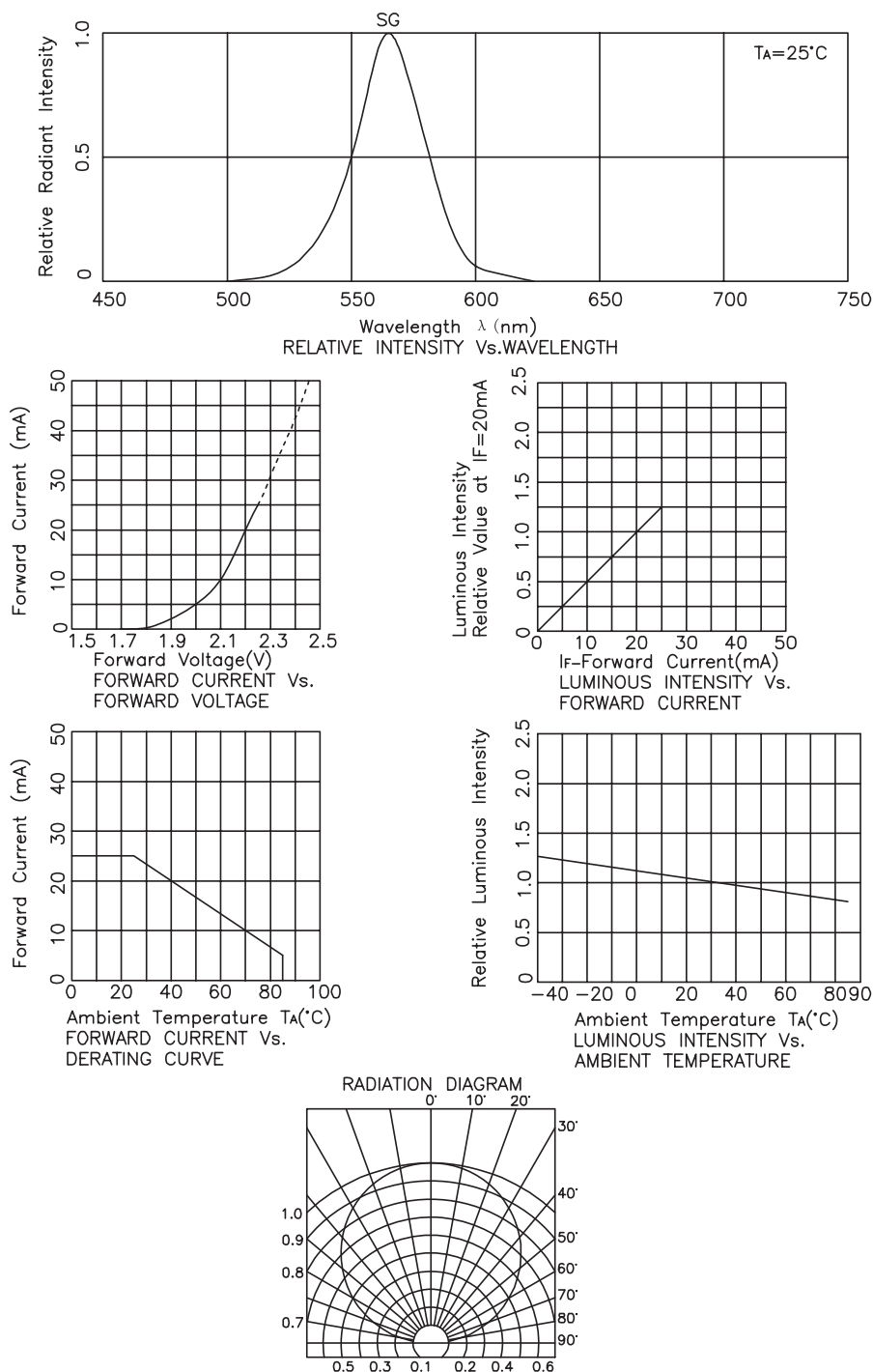
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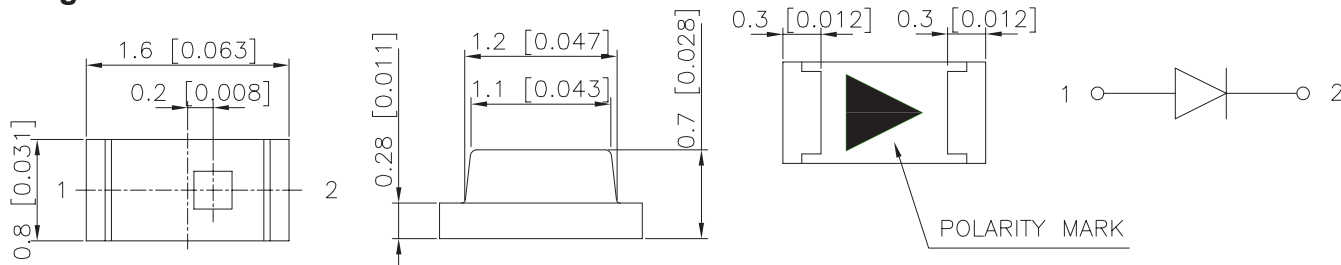
Typical Electrical/Optical Characteristics Curves



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Diagram

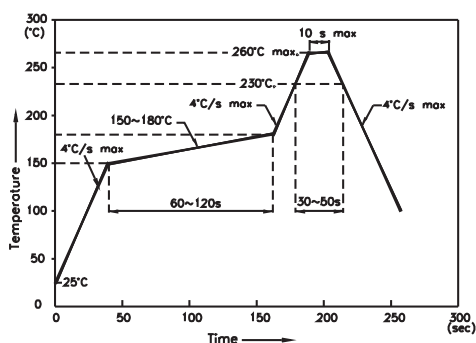


Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.15 unless otherwise noted.
3. Specifications are subject to change without notice.

Soldering Profile

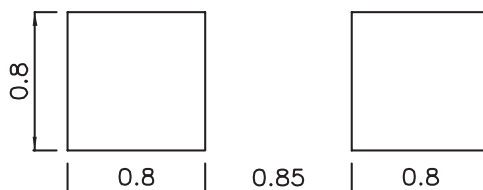
Reflow Soldering Profile For Lead-free SMT Process.



Notes

1. We recommend the reflow temperature 245°C. ($\pm 5^\circ\text{C}$) The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern



Part Number Table

Description	Part Number
SMD Chip LED, 0603, Yellow Green, 100mcd, 120°	MP005928

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